



Initial Product/Process Change Notification

Document #: IPCN22953X

Issue Date: 14 Feb 2020

Title of Change:	Assembly and Backgrind Transfer of SOIC 24 and 28 from ATP to OSPI	
Proposed First Ship date:	14 Jun 2020 or earlier if approved by customer	
Contact Information:	Contact your local ON Semiconductor Sales Office or Scott.Brow@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>	
Marking of Parts/ Traceability of Change:	Product assembled in OSPI will be identified by the assembly location code change on the product marking (Line 2 Trace code: L = ATP, P = OSPI) as well as the assembly location identifier on the label of the reel. Please see sample Label on page 2 at the following link http://www.onsemi.com/pub_link/Collateral/LABELRM-D.PDF	
Change Category:	Assembly Change	
Change Sub-Category(s):	Manufacturing Site Transfer	
Sites Affected:		
ON Semiconductor Sites	External Foundry/Subcon Sites	
ON Semiconductor Carmona, Philippines	None	
Description and Purpose:		
ON Semiconductor would like to inform customers of the intent to transfer backgrind and assembly for the products listed in this notification from the current assembly site, ATP (Amkor Technology Philippines) to an internal factory OSPI (ON Semiconductor Philippines). BOM (Bill of Materials) changes are listed below:		
	Before Change Description	After Change Description
Assembly Site	ATP	OSPI
Die Attach	Ablestick 8290/84-1 LMIS R4	Sumitomo CRM1084
Mold Compound	Sumitomo G600/Nitto MP8000AN	Sumitomo G600
Plating	PbSn	100% Sn
MSL	MSL 2 @ 225°C	MSL 2 @ 260°C
Product marking will be changed as listed here:		
	From	To
Product marking change	Trace Code Assembly Location Line 2: L(WLYYWW)G (Where WL = Wafer Lot Number YY = Year of Production, Last Two Numbers WW = Work Week Number)	Trace Code Assembly Location Line 2: P(WLYYWW)G (Where WL = Wafer Lot Number YY = Year of Production, Last Two Numbers WW = Work Week Number)



Qualification Plan:

QV DEVICE NAME : OSDIA-008 / 20501-001RMS : O63317 / O64144 / O63163

PACKAGE : 24W SOIC / 28W SOIC

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 2 @ 260 °C	

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
AMIS30512C5122RG	OSDIA-006-XTP